



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN155366

Date: March 16, 2015

Subject: Manufacturing Changes for Dual Port Specialty Memory Products at Advanced Semiconductor Manufacturing, Taiwan

To: PCN ADMIN
CYPRESS
pcn_adm@cypress.com

Change Type: Minor

Product Information:

Cypress announces the qualification of die attach film to replace die attach epoxy and the addition of a bottom spacer for select 172 and 484 ball grid array (BGA) stack-die packages of dual port specialty memory products at Advanced Semiconductor Manufacturing - Taiwan (ASE Kaohsiung). As part of this qualification, Cypress is changing the diameter of gold (Au) bond wire from 1.0 mil to 0.8 mil.

This change is to improve the process control resulting in better product quality, improved yield and field reliability. Die attach film, bottom spacer and 0.8 mil Au wire have been used in other Cypress products. This PCN is a fan-out activity to extend the coverage to dual port specialty memory products.

New and Current Bill of Materials:

Material	New Bill of Materials (ASE Taiwan)	Current Bill of Materials (ASE Taiwan)
Mold Compound	KE-G2270	KE-G2270
Die Attach	ATB-125-8 (Die Attach Film)	FH900 (Die Attach Epoxy)
Bond Wire	Au, 0.8 mil	Au, 1.0 mil
Bottom Spacer	Yes	No

This change has been qualified through a series of tests documented in Qualification Test Plan (QTP) 130803. The qualification report can be found as an attachment to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Affected Part Numbers: 8

Affected Parts: Please refer to the attached 'Affected Parts List' file

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated sample ordering part numbers. Sample requests for products without sample order part numbers are not built ahead of time, will be built to order and subject to standard lead times. Please contact your sales representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification, Cypress will start transition to shipments of the affected part numbers with the newly qualified die attach film, bottom spacer and 0.8 mil Au bond wire.

Anticipated Impact:

None anticipated. Products manufactured at ASE Taiwan with the new qualified die attach film, bottom spacer and 0.8 mil Au bond wire are completely compatible with existing product from a functional and parametric performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication and assembly location, through the lot number marked on the package. There will be no changes to the ordering codes or marking on production material shipped after the change implementation date.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	Sample Ordering Part Number
1	CY7C0853AV-100BBI	Available to order, subject to lead time
2	CY7C0853V-100BBC	Available to order, subject to lead time
3	CY7C0853V-133BBC	CY7C0853V-133BBCKG
4	CY7C0853V-133BBI	CY7C0853V-133BBIKG
5	CY7C0853V-133BBXI	CY7C0853V-133BBXIKG
6	CYD18S72V-100BBC	CYD18S72V-100BBCKG
7	CYD18S72V-100BBI	CYD18S72V-100BBIKG
8	CYD18S72V-133BBI	Available to order, subject to lead time